



## Description

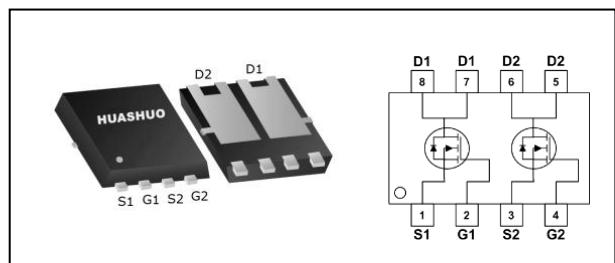
The HSBA6214 is the high cell density trenched N-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The HSBA6214 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

## Product Summary

$V_{DS}$	60	V
$R_{DS(ON),typ}$	35	mΩ
$I_D$	17	A

## PRPAK5\*6 Pin Configuration



## Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	60	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D @ T_C=25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	17	A
$I_D @ T_C=70^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	11	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	40	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	22	mJ
$I_{AS}$	Avalanche Current	21	A
$P_D @ T_A=25^\circ C$	Total Power Dissipation <sup>4</sup>	2	W
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

## Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient <sup>1</sup>	---	62	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	---	5	°C/W

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_{\text{D}}=250\mu\text{A}$	60	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	$\text{BV}_{\text{DSS}}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_{\text{D}}=1\text{mA}$	---	0.044	---	$\text{V}/^\circ\text{C}$
$R_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{\text{GS}}=10\text{V}$ , $I_{\text{D}}=15\text{A}$	---	35	42	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$ , $I_{\text{D}}=7\text{A}$	---	40	52	
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_{\text{D}}=250\mu\text{A}$	1.0	---	2.5	V
$\Delta V_{\text{GS}(\text{th})}$	$V_{\text{GS}(\text{th})}$ Temperature Coefficient		---	-4.8	---	$\text{mV}/^\circ\text{C}$
$I_{\text{DS}(\text{SS})}$	Drain-Source Leakage Current	$V_{\text{DS}}=48\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\text{uA}$
		$V_{\text{DS}}=48\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=55^\circ\text{C}$	---	---	5	
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=5\text{V}$ , $I_{\text{D}}=15\text{A}$	---	25.3	---	S
$R_g$	Gate Resistance	$V_{\text{DS}}=0\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	2.5	---	$\Omega$
$Q_g$	Total Gate Charge (4.5V)	$V_{\text{DS}}=48\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $I_{\text{D}}=15\text{A}$	---	19	---	$\text{nC}$
$Q_{\text{gs}}$	Gate-Source Charge		---	2.6	---	
$Q_{\text{gd}}$	Gate-Drain Charge		---	4.1	---	
$T_{\text{d}(\text{on})}$	Turn-On Delay Time	$V_{\text{DD}}=30\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $R_g=3.3\Omega$ $I_{\text{D}}=15\text{A}$	---	3	---	$\text{ns}$
$T_r$	Rise Time		---	34	---	
$T_{\text{d}(\text{off})}$	Turn-Off Delay Time		---	23	---	
$T_f$	Fall Time		---	6	---	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=15\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	1027	---	$\text{pF}$
$C_{\text{oss}}$	Output Capacitance		---	65	---	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	46	---	

**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current <sup>1,5</sup>	$V_G=V_D=0\text{V}$ , Force Current	---	---	17	A
$V_{\text{SD}}$	Diode Forward Voltage <sup>2</sup>	$V_{\text{GS}}=0\text{V}$ , $I_{\text{S}}=1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1.2	V
$t_{\text{rr}}$	Reverse Recovery Time	$I_F=4\text{A}$ , $dI/dt=100\text{A}/\mu\text{s}$ , $T_J=25^\circ\text{C}$	---	12.1	---	nS
$Q_{\text{rr}}$	Reverse Recovery Charge		---	6.7	---	$\text{nC}$

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{\text{DD}}=25\text{V}$ ,  $V_{\text{GS}}=10\text{V}$ ,  $L=0.1\text{mH}$ ,  $I_{\text{AS}}=21\text{A}$
- 4.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 5.The data is theoretically the same as  $I_{\text{D}}$  and  $I_{\text{DM}}$  , in real applications , should be limited by total power dissipation.



Typical Characteristics

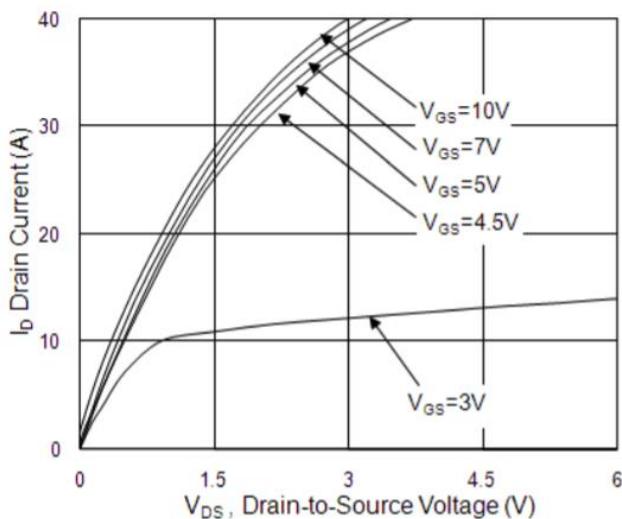


Fig.1 Typical Output Characteristics

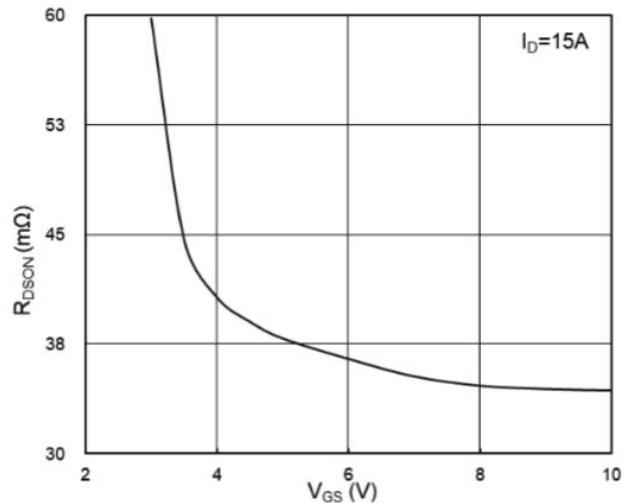


Fig.2 On-Resistance vs. Gate-Source

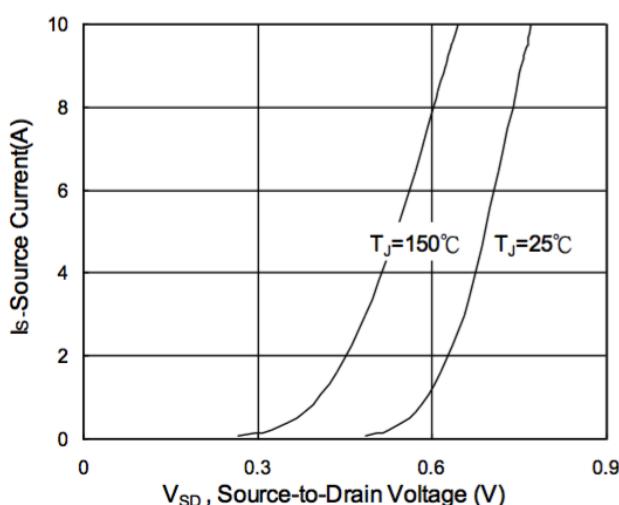


Fig.3 Forward Characteristics Of Reverse

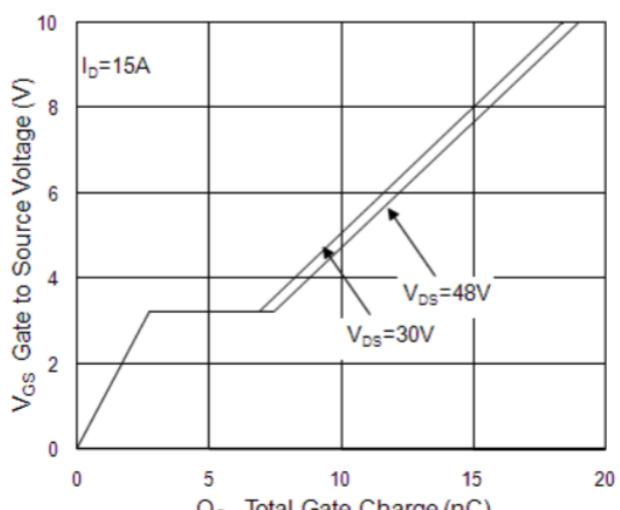


Fig.4 Gate-Charge Characteristics

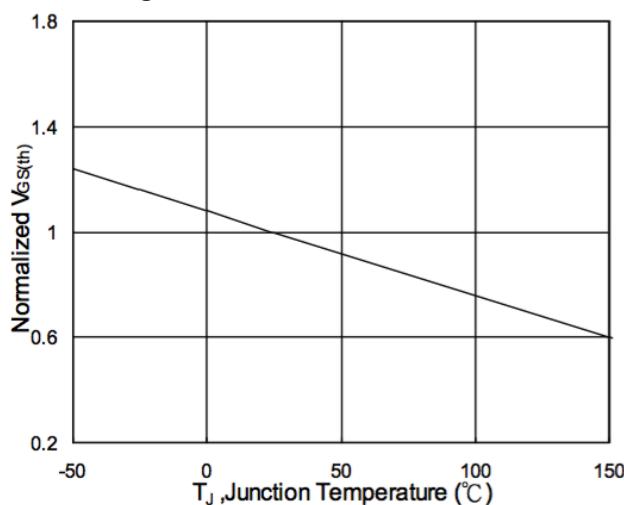


Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$

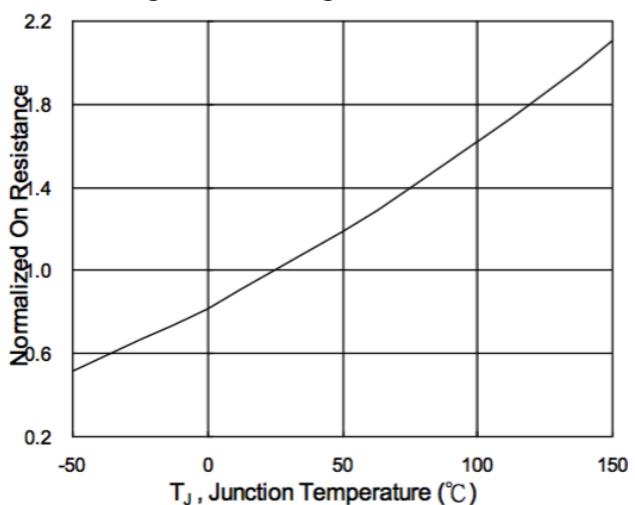


Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$



HUASHUO  
SEMICONDUCTOR

HSBA6214

Dual N-Ch 60V Fast Switching MOSFETs

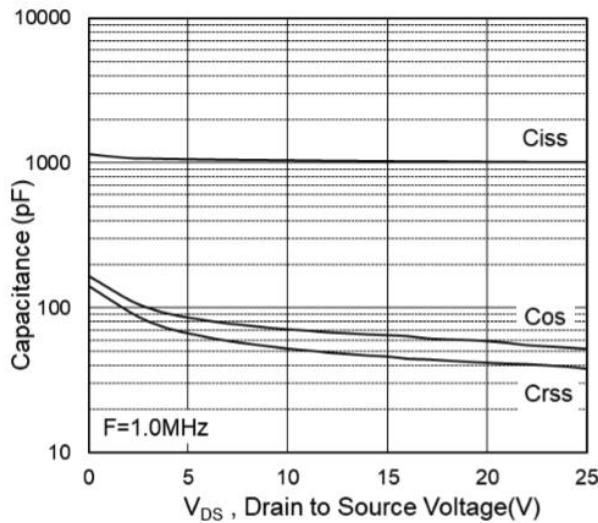


Fig.7 Capacitance

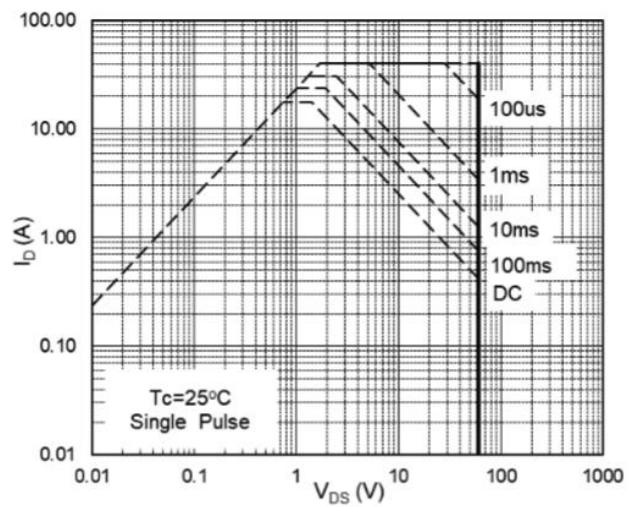


Fig.8 Safe Operating Area

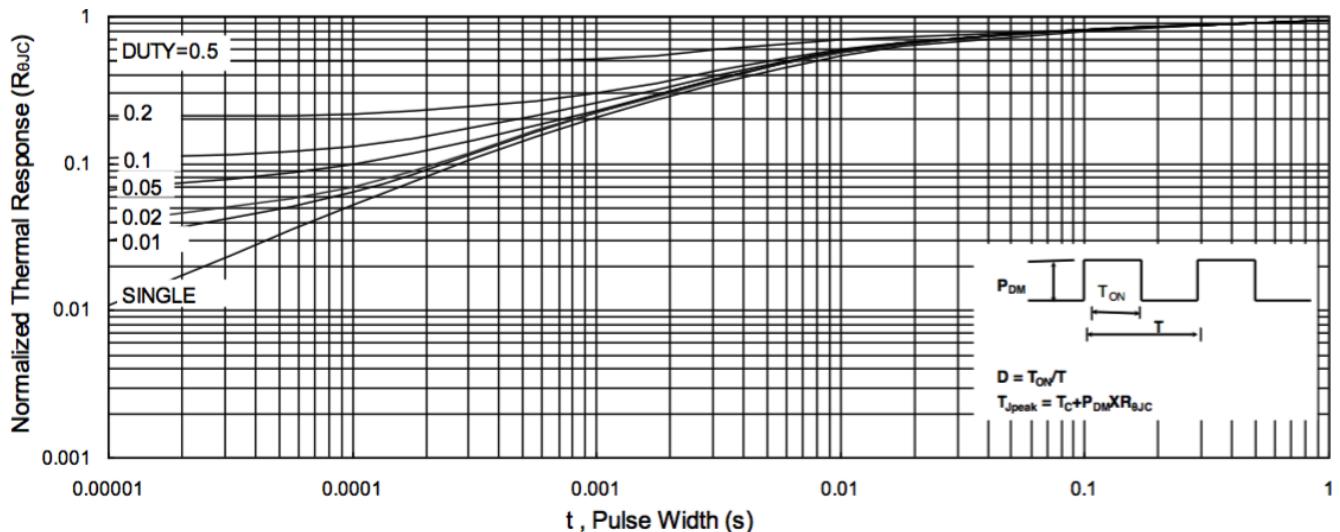


Fig.9 Normalized Maximum Transient Thermal Impedance

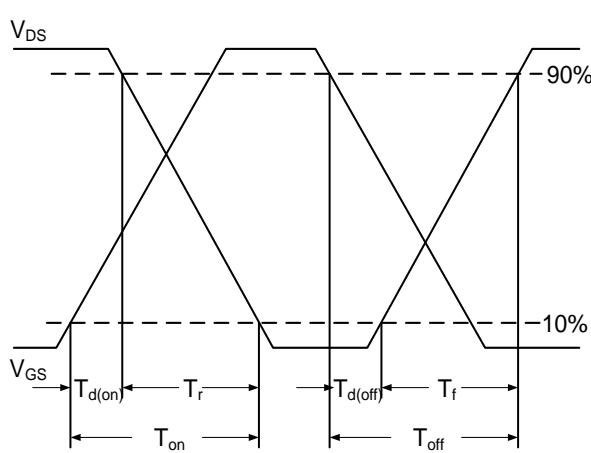


Fig.10 Switching Time Waveform

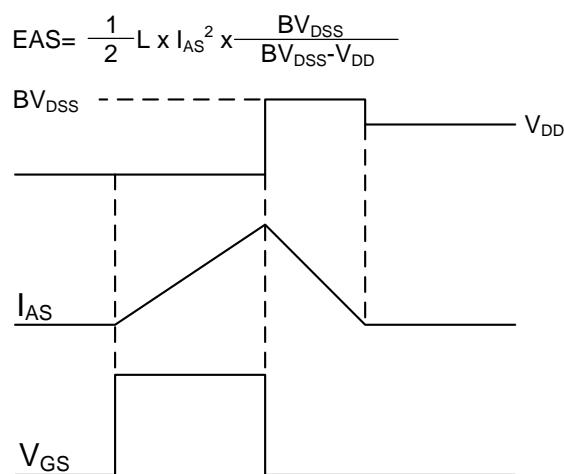
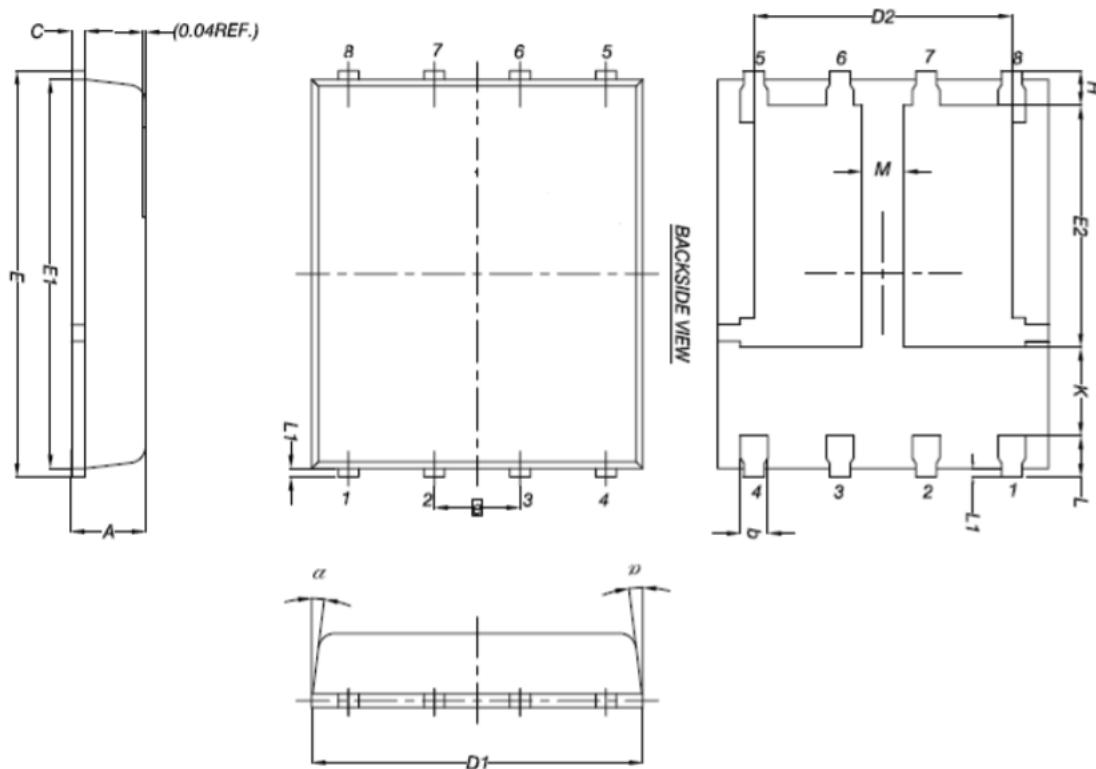


Fig.11 Unclamped Inductive Switching



## PRPAK5x6-8L Dual EP2 Package Outline



SYMBOLS	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.90	1.17	0.035	0.046
b	0.33	0.51	0.013	0.020
C	0.20	0.30	0.008	0.012
D1	4.80	5.20	0.189	0.205
D2	3.61	3.96	0.142	0.156
E	5.90	6.15	0.232	0.242
E1	5.70	5.85	0.224	0.230
E2	3.30	3.78	0.130	0.149
e	1.27 BSC		0.05 BSC	
H	0.38	0.61	0.015	0.024
K	1.10	---	0.043	---
L	0.38	0.61	0.015	0.024
L1	0.05	0.25	0.002	0.010
M	0.50	---	0.020	---
α	0°	12°	0°	12°